In the Specification

Please amend the specification as follows in accordance with 37 C.F.R. §1.121:

[0043] Referring now to figure 3, therein is depicted a wafer-interposer assembly of the present invention that is generally designated 40. Wafer-interposer assembly 40 includes a wafer interposer 42 and a wafer 18 that is electrically and mechanically attached thereto as explained above. Wafer interposer 42 includes a wafer receiving portion onto which wafer 18 has been positioned and a handling portion 44 that extends outwardly from the wafer receiving portion such that handling portion 44 is accessible without contacting wafer 18. In the illustrated embodiment, handling portion 44 includes a plurality of slots that provide for the use of highly reliable handling equipment for moving wafer-interposer assembly 40 from one location to another and provide for secure positioning of wafer-interposer assembly 40 within processing equipment, containers and the like. Specifically, handling portion 44 of interposer 42 has a pair of upper slots 46 and 48, a pair of lower slots 50 and 52 and a pair of side slots 54 and 56. As an example, these slots provide for the secure insertion and proper alignment of wafer-interposer assembly 40 into a testing apparatus. In addition slots 46 and 48 include stops 58 and 59, respectively, that assure proper ~~orientiion~~ orientation and

positioning of wafer-interposer assembly 40 into, for example, testing equipment. Likewise, these slots provide for the secure insertion of wafer-interposer assembly 40 into a cassette type transfer container or secure insertion or stacking within a storage/transportation container. In any of the above examples, wafer-interposer assembly 40 may be moved using transfer equipment that securely accesses one or more of the slots or other parts of handling portion 44.

[0044] Even though figure 3 has depicted interposer 42 as having three pairs of slots, upper slots 46 and 48, a pair of lower slots 50 and 52 and a pair of side slots 54 and 56, it should be understood by those skilled in the art that interposer 42 could have other numbers of slots, either more or less, depending upon the configuration of the transfer or processing equipment or the containers to be used in conjunction with wafer-interposer assembly 40, without departing from the principles of the present invention. In addition, even though figure 2 has depicted the slots of interposer 42 as traversing the entire length of interposer 42, it should be understood by those skilled in the art that interposer 42 could alternatively have slots that extend only part way across interposer 42, without departing from the principles of the present invention. Also, even though figure 3 has depicted slots that are ~~symetrically~~ symmetrically cut into interposer 42, non ~~symetrically~~

symmetrically positioned slots may alternatively be used without departing from the principles of the present invention.

[0048] Even though figure 5 has depicted interposer 72 as having four holes 76, 78, 80 and 82 in the respective corners of interposer 72, it should be understood by those skilled in the art that interposer 72 could include other numbers of holes, either more or less, in other positions in handling portion 74, without departing from the principles of the present invention. Also, even though the holes have been depicted as being ~~symetric~~ symmetric, the holes could alternatively be positioned in a non ~~symetric~~ symmetric orientation without departing from the principles of the present invention.